



SOT481-2

plastic thin shrink small outline package; 56 leads; body width 4.4 mm

8 February 2016

Package information

1. Package summary

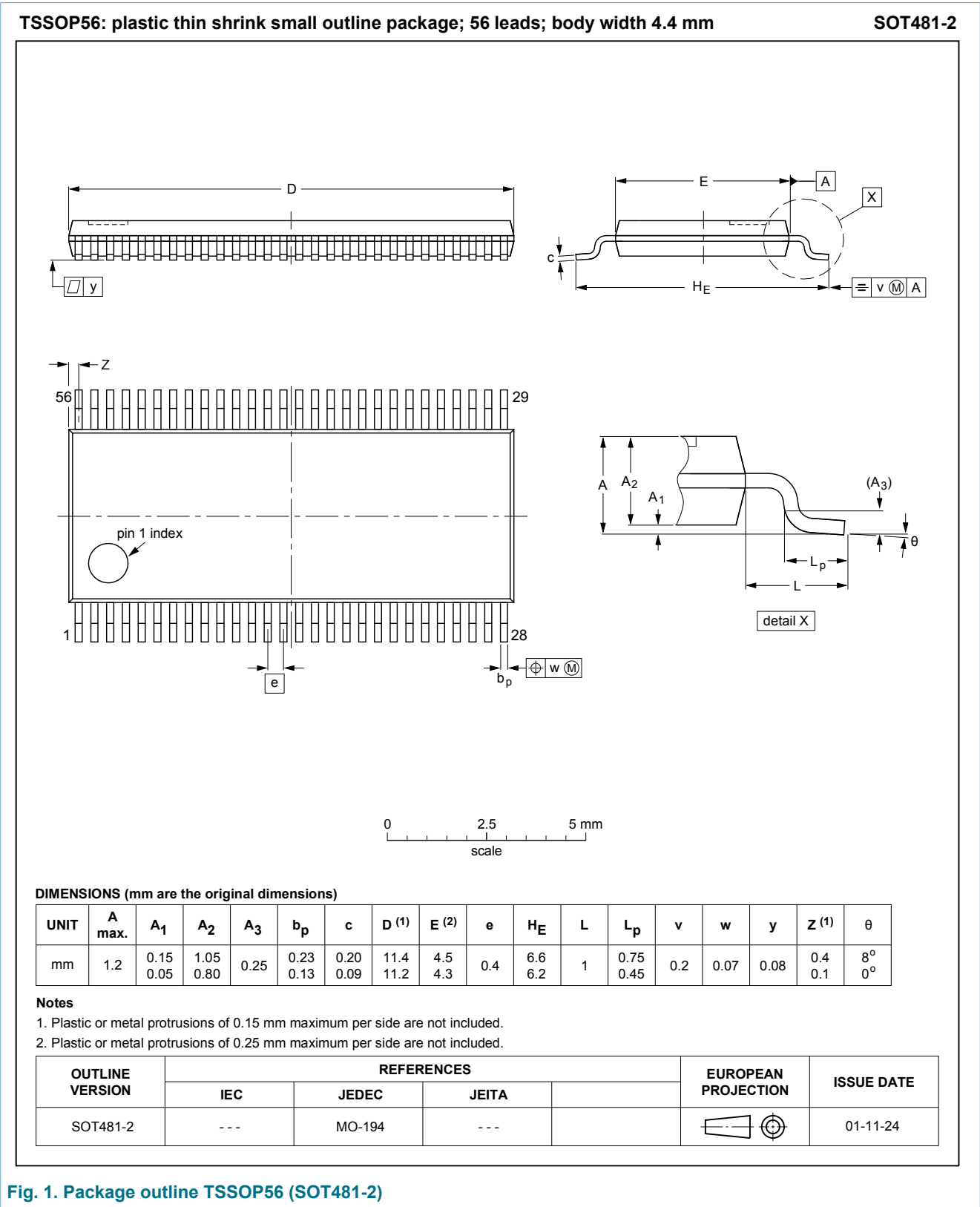
Terminal position code	D (double)
Package type descriptive code	TSSOP56
Package type industry code	TSSOP56
Package style descriptive code	TSSOP (thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-194
Mounting method type	S (surface mount)
Issue date	24-11-2001

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.2	-	11.3	11.4	mm
E	package width		4.3	-	4.4	4.5	mm
A	seated height		[tbd]	-	1.2	1.2	mm
A ₂	package height		0.8	-	0.9	1.05	mm
n ₂	actual quantity of termination		-	-	56	-	



2. Package outline



3. Soldering

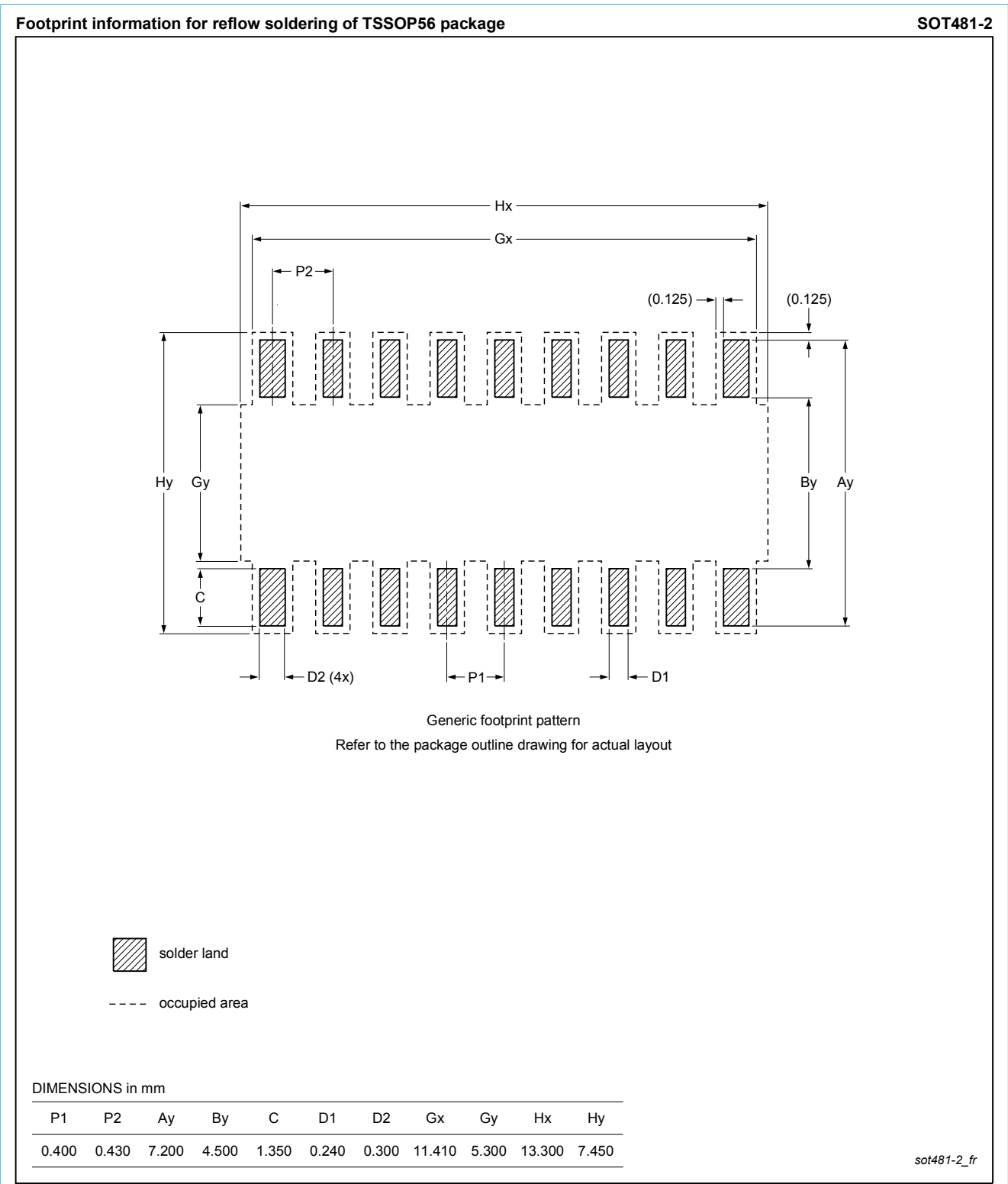


Fig. 2. Reflow soldering footprint for TSSOP56 (SOT481-2)

4. Legal information

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